

Fresco Logic Demonstrates Industry's First Multi-vendor USB 3.0 System-level interoperability Using its xHCI Host Adapter and the Fujitsu USB 3.0 SATA Bridge Device

Demo Highlights the Performance and Usability at the SuperSpeed USB Developers Conference, Tokyo, May 20-21

SuperSpeed USB Developers Conference, Tokyo, Japan – May 20, 2009 – Fresco Logic, a leading fabless semiconductor company focused on SuperSpeed connectivity solution, demonstrates the industry's first system-level interoperability between Fresco Logic's SuperSpeed USB extensible host controller interface (xHCI) adapter and a USB3.0 SATA bridge device from Fujitsu Microelectronics Limited at the SuperSpeed USB Developers Conference, Tokyo, Japan.

SuperSpeed USB, also known as USB 3.0, is looked up to deliver a remarkable throughput at 5Gbps, 10 times greater than can be obtained using Hi-Speed USB (USB 2.0). Featuring backward compatible, lower power consumption, and simultaneous bi-directional data transmission, USB 3.0 enables infinite possibility in CE markets from PC storage, SSD, HD multimedia, to mobile internet devices.

The multi-vendor system-level interoperability demonstration provides a preview of the true user experience that consumers can have with USB3.0, moving HD content and multi-Gigabyte sized files between a PC and an external storage device, achieving significant performance over USB 2.0. This demonstration is also based on existing Windows Mass Storage Client Driver, Newly developed xHCI prototype Driver, a solid state drive (SSD) , an external hard drives (HDD) from respective parties.

"The first SuperSpeed USB interoperability demonstration using Fresco's host adapter and the Fujitsu USB 3.0 SATA bridge device is a huge step forward. It is also a prelude to providing consumers significantly faster data transfers driven by SuperSpeed USB technology," said Fujio Nakanishi, President of ASSP Business Unit at Fujitsu Microelectronics Limited. "The USB 3.0 specifications were set last November, so this is a significant achievement in such a short period of time. We expect our chip to be embedded in devices to be released the end of this year," he added.

“The success of multi-vendor interoperability is exciting news for USB 3.0 ecosystem” said Jing-fan Zhang, President & CEO of Fresco Logic. “The demonstration shows how USB 3.0 will provide the needed performance boost to handle large data files today and even larger ones tomorrow. The demo shows how mass-storage applications can immediately benefit from greater than 10x times performance boost using existing technologies. With this demonstration, we can really begin to see the value that SuperSpeed USB brings to the end user.”

About Fresco Logic

Fresco Logic is a fabless chip company focused on providing advanced solutions for moving and storing content to deliver the high-efficient connectivity and storage across consumer electronics, personal computing, and mobile internet devices. Fresco Logic works closely with strategic customers and partners to present new products on emerging connectivity standards such as SuperSpeed USB. Providing a comprehensive offering of silicon, systems, and solutions, Fresco Logic gives product development companies the right mix of cost-effective offerings to bring connectivity and storage options to market faster.

The names of actual companies and products mentioned herein may be the trademarks of their respective owners.

For more information, press only:
Michelle.chan@frescollogic.com

For more information on Fresco Logic Products visit:
<http://www.frescollogic.com/>